



■ Typical Specifications

Items	Specifications
Rating (max.)	50mA 12V DC
Rating (min.)	10µA 1V DC
Travel (mm)	0.13

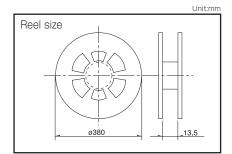
■ Product Line

Product No.	Operating force	Operating Operating life	perating force Operating Operating life Initial contact	Minimum ord	Drawing				
T TOUGGE TVO.	direction (5mA 5V DC) resistance		resistance	Stem height	Japan	Export	No.		
SKRKAEE010	1.57N		Top push 200,000 cycles 500mΩ max. 2mm	$100 \text{m}\Omega$ max.	Omm	4.500	4.500	1	
SKRKAHE010	0.98N	Top push		2111111	4,000	4,300	'		
SKRKAGE010	1.57N					100mΩ max.	1.5mm	5,000	5,000

Packing Specifications

Taping

Series	Numb	er of packages	Tape width	Export package	
Selles	1 reel	1 case /Japan	1 case / export packing	(mm)	measurements (mm)
SKRKAE SKRKAH	4,500	45,000	45,000	12	401×401×214
SKRKAG	5,000	50,000	50,000	IC.	401/401/214



Note

For reels of 330mm diameter, please inquire.

וט	mensions		Unit:mm
No.	Photo	Style	PC board land dimensions (Viewed from switch mounting face)
1		4.8 3.9 01.8 Stem	Resist coating 3.4 5

Refer to P.259 for soldering conditions.

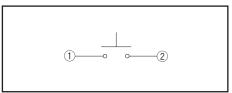




Dimensions Unit:mm

No.	Photo	Style	PC board land dimensions (Viewed from switch mounting face)
2		(depth 0.3) (depth	Resist coating 3.4 5

Circuit Diagram



Downloaded from Arrow.com.

	Type	Sharp Feeling Type							
71.					Surface	e Mount			
	Series 	SKSD	SKRN	SKSV	SKSW	SKSF	SKSM	SKSG	SKRK
	Photo					•	0		0
	Features	Double	action		Compa Low-p			High operation force Compact size	Compact size Low-profile
	Water-proof	_	_	•	•	_	•	_	_
	Dust-proof	_	_	•	•	_	•	_	_
	IP standard	_	_	67 equivalency	67 equivalency	_	_	_	_
Operatir	Top push	•	•	•	•	•	•	•	•
directio		_	_	_	_	_	_	_	_
	W	4.1		2.8	3	2.8	3.4	3	3.9
Dimensio (mm)		3.9	□6	1.9	2	2.4	2.9	2.7	2.9
()	Н	0.6	0.9	0.55	0.6	0.65	0.7	1.4	1.5/2
Operation force coverage	2N to 3N	See the rele for respect descri	ive product	1	\$	\$	‡	1	1
	Travel (mm)	See the releven respective produced in the control of the control		0.12	0.13	a	.1	0.12	0.13
G	round terminal	•	•	_	_	_	_	0	_
Operatin	ng temperature range	-40°C to	0 +90℃		_	-30°C to +85°	С		-40℃ to +85℃
А	utomotive use	_	_	_	_	_	_	•	_
	Life Cycle	* 2	* 2	X 2	* 2	X 2	* 2	X 2	X 2
	Rating (max.) (Resistive load)				50mA 1	I2V DC			
Electrical	Rating (min.) (Resistive load)				10μΑ	1V DC			
performance	Insulation resistance		100MΩ min. 100V DC 1min. 50MΩ min. 100V DC 1min. 100V DC 1min.					100MΩ min. 1	00V DC 1min.
	Voltage proof	100V AC 1min.	250V AC 1min.			100V AC 1min			250V AC 1min.
D bilit	Vibration		10 to	55 to 10Hz/m in the 3 direct	in., the amplitu	de is 1.5mm fo d Z for 2 hours	or all the freque respectively	encies,	
Durability	Lifetime			Shall be in a	accordance wit	h individual sp	ecifications.		
	Cold				-40°C	C 96h			
Environmental performance	Dry heat				90℃	96h			
	Damp heat	60°C, 90 to 95%RH 96h							
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W: Width. The most outer dimension excluding terminal portion. D: Depth. The most outer dimension excluding terminal portion. H: Height. The minimum dimension if there are variances.

- Notes

 1. The automotive operating temperature range to be individually discussed upon request.
- 2. lacktriangle Indicates applicability to all products in the series, while \bigcirc indicates applicability to some products in the series.

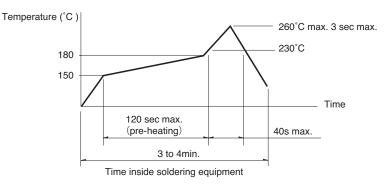




Condition for Reflow

Available for Surface Mount Type.

- 1. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at solder joints (copper foil surface).
 - A heat resistive tape should be used to fix thermocouple.
- 2. Temperature profile



TACT Switch™ Soldering Conditions

- 1. The above temperature shall be measured of the top of switch. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the material, size, thickness of PC boards and others. The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Conditions for Auto-dip

Available for Snap-in Type and Radial Type.

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKHH, SKPD Series

Items	Condition		
Flux built-up	Mounting surface should not be exposed to flux		
Preheating temperature	Ambient temperature of the soldered surface of PC board. 110°C max.		
Preheating time	60s max.		
Soldering temperature	260°C max.		
Duration of immersion	5s max.		
Number of soldering	2times max.		

SKQJ, SKQK, SKEG Series

Items	Condition	
Flux built-up	Mounting surface should not be exposed to flux	
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.	
Preheating time	45s max.	
Soldering temperature	255℃ max.	
Duration of immersion	5s max.	
Number of soldering	2times max.	

Manual Soldering

Items	Condition
Soldering temperature	350℃ max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

SKHH, SKHW, SKRG, SKPD Series

Items	Condition
Soldering temperature	360℃ max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

SKTD, SKTG, SKQJ, SKQK, SKEG Series

Items	Condition
Soldering temperature	350°C max.
Duration of soldering	3s max.
Capacity of soldering iron	20W max.

- 1. Prevent flux penetration from the top side of the TACT Switch™.
- 2. Switch terminals and a PC board should not be coated with flux prior to soldering.
- 3. The second soldering should be done after the switch is stable with normal temperature.
- 4. Use the flux with a specific gravity of min 0.81. (EC-19S-8 by TAMURA Corporation, or equivalents.)



